Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP  Semiconductor Device Type: H5A 006 VDFN 3.2x2.5x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
	11011	"Contained In"	% Total			8.78	(max Tatal	Mold Compound	% ot Total Weight	45.00
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	8.78	(mg) Total	Moia Compouna	% of Total Weight	45.00
Silica Fused	60676-86-0	Mold Compound	41.265	8.047	412,650		Silica Fused	60676-86-0	91.70	
Epoxy Resin	Trade secret	Mold Compound	1.800	0.351	18,000		Epoxy Resin	Trade secret	4.00	
Phenol Resin	Trade secret	Mold Compound	1.800	0.351	18,000		Phenol Resin	Trade secret	4.00	
Carbon Black	1333-86-4	Mold Compound	0.135	0.026	1,350		Carbon Black	1333-86-4	0.30	]
Copper	7440-50-8	Lead Frame	45.196	8.813	451,959			Total	100.00	
Iron	7439-89-6	Lead Frame	1.068	0.208	10,684	9.06	(mg) Total	Lead Frame	% of Total Weight	46.45
Phosphorous	7723-14-0 7440-66-6	Lead Frame	0.116	0.023	1,161 697		Copper	7440-50-8	97.30 2.30	
Zinc (Metal) Fused silica	60676-86-0	Lead Frame Die Attach	0.070 0.557	0.014 0.109	5,565		Iron	7439-89-6	0.25	
Silver	7440-22-4	Die Attach	0.375	0.109	3,746		Phosphorous Zinc (Metal)	7723-14-0 7440-66-6	0.25	
Epoxy Resin	Trade Secret	Die Attach	0.375	0.073	1.493		Zino (Weldi)	7440-66-6 Total	100.00	l
Acrylate resin	Trade Secret	Die Attach	0.149	0.029	1,493	0.24	(mg) Total	Die Attach	% of Total Weight	1.25
Biphenol A Glycidylether	25068-38-6	Die Attach	0.063	0.021	625	0.24	Fused silica	60676-86-0	44.52	1.20
Silicon	7440-21-3	Dual Chip (Die)	6.150	1.199	61,500		Silver	7440-22-4	29.97	
Gold	7440-57-5	Wire Bond	0.500	0.098	5.000		Epoxy Resin	Trade Secret	11.95	
Nickel	7440-02-0	Plating on external leads (pins)	0.585	0.114	5.850		Acrylate resin	Trade secret	8.57	
Palladium	7440-05-3	Plating on external leads (pins)	0.033	0.006	325		Biphenol A Glycidylether		5.00	
							Dipriction / Cityclayletile			l
Gold	7440-57-5	Plating on external leads (pins)	0.033	0.006	325			Total	100 00	
Gold	7440-57-5	Plating on external leads (pins)  TOTALS:	0.033 <b>100.000</b>	0.006 <b>19.500</b>	325 1,000,000	1.20	Total (mg)	Total Dual Chip (Die)	100.00 % of Total Weight	6.15
emiconductor device and its homogenous mat 63/EU (31 March 2015) and 2002/53/EC (End-o	0.0195 erials comply wir f-Life Vehicles (E	TOTALS:  g Total Mass th EU Directives: 2002/95/EC (27 January 2003) ELV) without exemption (zero)	100.000 & Directive 201	19.500 1/65/EU (08 Ju	1,000,000		Doped Silicon	Dual Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	
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